



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-02-25
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS2545CGY-TR	ASD2*Z06SA2Y	A	SHENZHEN B/E	2016-02-25
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380.00	mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 9.15, 4.5	2	GULL WING	
Comment	D2PAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ASD2*Z065A2Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	8.769	mg	supplier	die	Silicon (Si)	7440-21-3		8.249	mg	940700	5978
				supplier	metallization	Aluminium (Al)	7429-90-5		0.341	mg	38887	247
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	912	6
				supplier	metallization	Tungsten (W)	7440-33-7		0.012	mg	1368	9
				supplier	metallization	Nickel (Ni)	7440-02-0		0.037	mg	4219	27
				supplier	Passivation	Silicon Oxide	7631-86-9		0.050	mg	5702	36
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	456	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	1368	9
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.056	mg	6386	41
				Leadframe	Copper & Its alloys	779.567	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.358	mg	459	259
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.654	mg	839	474
supplier	metallization	Nickel (Ni)	7440-02-0						1.012	mg	1298	733
supplier	metallization	Phosphorus (P)	12185-10-3						0.006	mg	8	4
Soft solder	Solder	7.839	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	7.486	mg	954969	5425
				supplier	solder	Silver (Ag)	7440-22-4		0.196	mg	25003	142
				supplier	solder	Tin (Sn)	7440-31-5		0.157	mg	20028	114
Bonding wires	Other inorganic materials	5.144	mg	supplier	wire	Aluminium (Al)	7429-90-5		5.144	mg	1000000	3728
				supplier	wire	Aluminium (Al)	7429-90-5		5.144	mg	1000000	3728
Encapsulation	Other Organic Materials	576.192	mg	supplier	mold compound	Silica, vitreous	60676-86-0		464.411	mg	806000	336530
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		40.333	mg	69999	29227
				supplier	mold compound	Phenol resin	9003-35-4		23.048	mg	40001	16701
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		34.572	mg	60001	25052
				supplier	mold compound	Antimony Trioxide	1309-64-4		6.914	mg	11999	5010
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		4.033	mg	6999	2922
				supplier	mold compound	Carbon black	1333-86-4		2.881	mg	5000	2088
Connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804